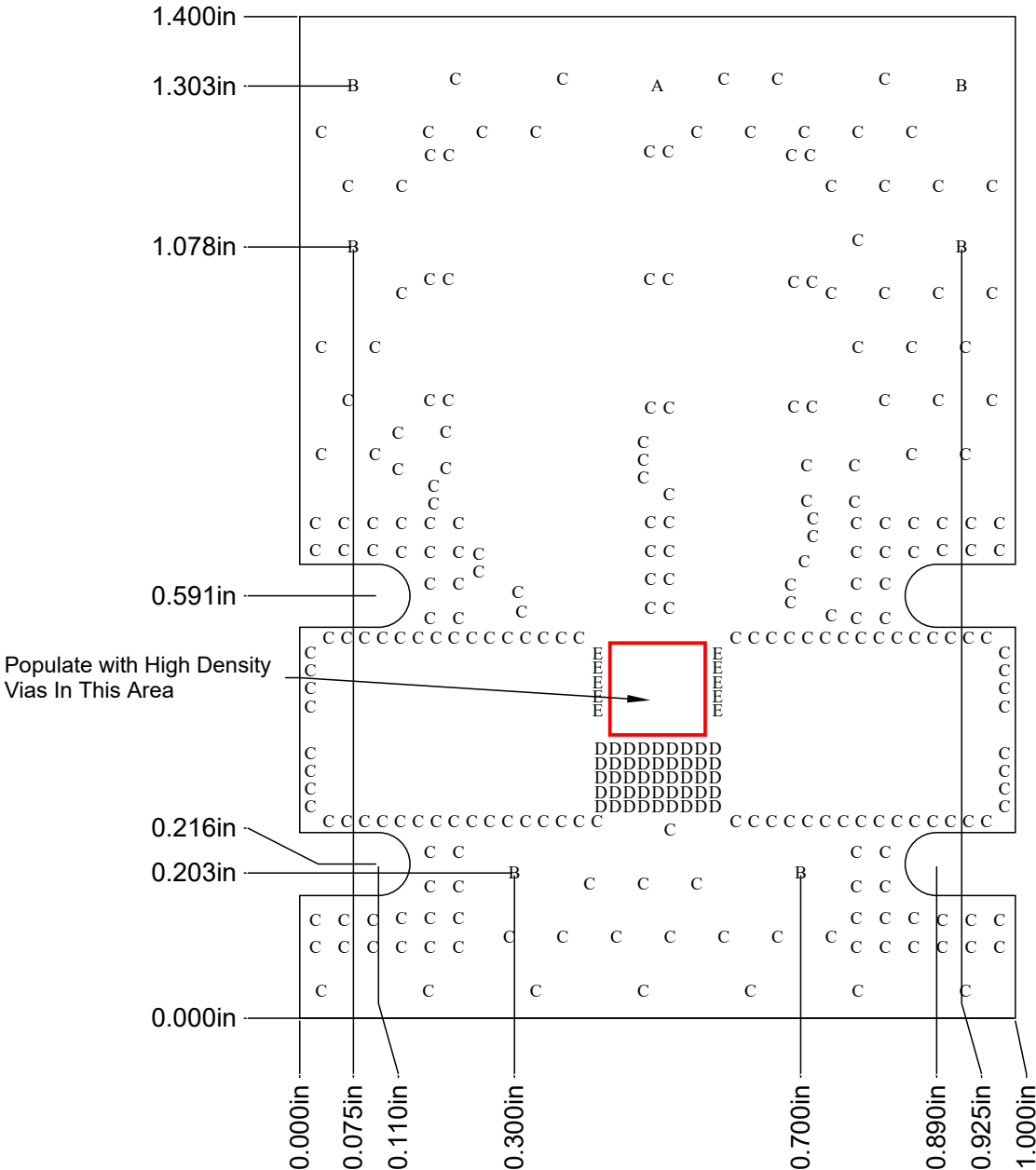


SUPPLIER MUST SEND EMAIL TO EVBHOLD@QORVO.COM IF JOB IS PLACED ON HOLD
SUPPLIER SHALL SEND A COPY OF FINAL WORKING GERBERS TO CEADS@QORVO.COM


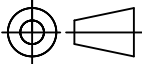
NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARD FABRICATION METHODS MUST COMPLY WITH:
FABRICATE IN ACCORDANCE WITH IPC-6018B, per IPC-6011, CLASS 2.
2. ARTWORK FORMAT: GERBER 274X
GERBER DATA SUPPLIED WITH DESIRED FINAL TRACE WIDTHS. PROCESS
COMPENSATION TRACE WIDTH ADJUSTMENTS TO BE DONE BY PCB FABRICATOR
3. NUMBER OF LAYERS: 2 LAYERS
METAL 1 0.5oz. (Plus Plating)
CORE 1: ROGERS 6035HTC, .010in. THICK
METAL 2 0.5oz. (Plus Plating)
SOLDERMASK TOP: LPI (LIQUID PHOTO-IMAGEABLE), GREEN OR LDI (LASER DIRECT IMAGEABLE),
GREEN. MAX FINISH THICKNESS OF SOLDERMASK TO BE 0.001in.
SILKSCREEN TOP: HIGH TEMPERATURE, NON-CONDUCTIVE, WHITE EPOXY BASED INK.
4. FINISH PLATING:
ENIG(ELECTROLESS NICKEL/IMMERSION GOLD)
5. FINISHED BOARD THICKNESS: (0.014in) ±.003IN.
6. COPPER IS PULLED BACK PER GERBER DATA FROM EDGE OF BOARD ON METAL 1 (TOP)
AND METAL 2 (BOTTOM) EXCEPT AROUND CONNECTOR AREA.
7. TOLERANCE:
A. PC BOARD OUTLINE: ±0.003in.
8. METAL TO EDGE IS NECESSARY. THE PRODUCT PERFORMANCE IS SIGNIFICANTLY
COMPROMISED WITH LARGE PULL BACKS. WE WILL ACCEPT BURRS.
9. VIA PLATING/FILLING:
A. ALL VIAS ARE TO BE NON-CONDUCTIVE EPOXY FILLED, OVER-PLATED AND PLANARIZED.
B. ALL OTHER PLATED THRU HOLES TO BE PLATED TO 0.0007 MIN. THICKNESS.
10. SINGULATION: EXTERNAL OUTLINE IS TO BE COMPLETED
VIA OPTICAL (LENZ) ROUTING OR LASER.
11. FINISHED Cu THICKNESS TO BE .0018 ± .0005.
12. CONDUCTOR WIDTHS AND SPACING TO BE WITHIN 0.001in. OF CAD DATABASE.
13. SOLDERMASK IN PLATED-THRU HOLES IS ACCEPTABLE AS LONG AS IT DOES
NOT EXIST ON BACKSIDE OF BOARD.
14. ALL HOLES TO BE LOCATED WITHIN ±0.003 OF CAD DATABASE.
15. NO VENDOR MARKING ALLOWED EXCEPT DATE CODE FOR TRACEABILITY.
16. BOARDS TO BE SINGULATED PER MECHANICAL 2 AND DELIVERED BAGGED AS SINGLES
17. NO ELECTRICAL TEST NEEDED.



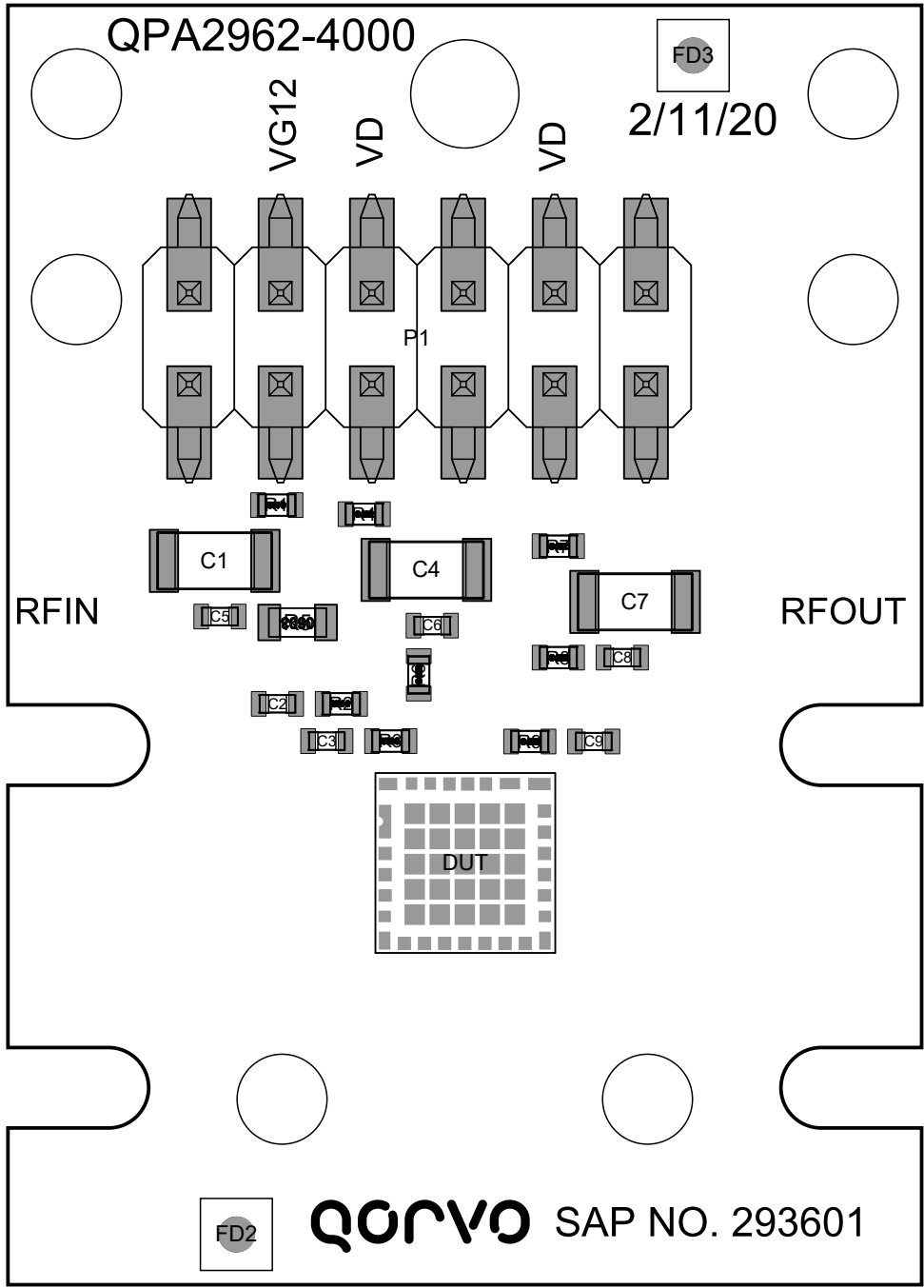
REFERENCE NOTE: Uses QPA2962-4000[1] CAL SAP No. 293660

* FOR MULTIPLE DRILL PROCESS JOBS SEE: *.DRL, *.DR1, *.DR2, etc.

| | | | | | | | |
|---|--|----------|---|-----------|---|---------------------|------------|
| UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES | SAP MATERIAL NUMBER: 293601 | |  | | | | |
| | APPROVAL AND RELEASE RECORDS MAINTAINED IN PDE | | | | | | |
| | DESIGNER | OMARRUFO | DATE | 1/22/2020 | TITLE: QPA2962 EVALUATION PCB DESIGN PACKAGE | | |
| | ENGR. | W.SHU | | | | | |
| INTERPRET DRAWING PER ANSI/ASME Y14.5 - 2009 | PDE CONTROLLED | | SIZE | | DOCUMENT NUMBER: | PROTOTYPE INSTANCE: | REV. |
|  | | | B | | QPA2962-4000 | N/A | A |
| THIRD ANGLE PROJECTION | | | SHEET 1 OF 5 | | CAD: ALTIUM DESIGNER | | SCALE: 2:1 |
| DO NOT SCALE DRAWING | | | | | | | |

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1. THE PCB WILL MOST LIKELY NOT BE FULLY POPULATED.



LAYER STACK LEGEND_SEE NOTE 3 FOR MATERIAL (COPPER THICKNESS IS @ FINISHED THICKNESS)

| Material | Layer | Thickness | Dielectric | Material | Type | Gerber |
|---------------------------|----------------|-----------|-----------------|----------|-------------|--------|
| | SILKSCREEN_TOP | | | | Legend | GTO |
| Surface Material | SOLDERMASK_TOP | 0.0004in | Solder Resist | | Solder Mask | GTS |
| Copper | METAL1_TOP | 0.0018in | | | Signal | GTL |
| Core | | 0.0100in | ROGERS 6035 HTC | | Dielectric | |
| Copper | METAL2_BOT | 0.0018in | | | Signal | GBL |
| Total thickness: 0.0140in | | | | | | |

Drill Table (HOLE SIZES ARE DRILLED SIZE)

| Symbol | Count | Hole Size | Plated | Drill Layer Pair |
|--------|-----------|--------------|--------|-------------------------|
| D | 45 | 10.00(0.25) | Plated | METAL1_TOP - METAL2_BOT |
| E | 10 | 10.00(0.25) | Plated | METAL1_TOP - METAL2_BOT |
| C | 248 | 15.00(0.38) | Plated | METAL1_TOP - METAL2_BOT |
| B | 6 | 100.00(2.54) | Plated | METAL1_TOP - METAL2_BOT |
| A | 1 | 120.00(3.05) | Plated | METAL1_TOP - METAL2_BOT |
| | 310 Total | | | |

* FOR MULTIPLE DRILL PROCESS JOBS SEE: *.DRL, *.DR1, *.DR2, etc.

| | | | | | | | |
|--|--|----------|----------------------|---|---------------------|------|------|
| UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES | SAP MATERIAL NUMBER: 293601 | | | | | | |
| | APPROVAL AND RELEASE RECORDS MAINTAINED IN PDE | | | | | | DATE |
| | DESIGNER | OMARRUFO | 1/22/2020 | TITLE: QPA2962 EVALUATION PCB DESIGN PACKAGE | | | |
| | ENGR. | W.SHU | | | | | |
| INTERPRET DRAWING PER ANSI/ASME Y14.5 - 2009 | PDE CONTROLLED | | SIZE | DOCUMENT NUMBER: | PROTOTYPE INSTANCE: | REV. | |
| | | | B | QPA2962-4000 | N/A | A | |
| THIRD ANGLE PROJECTION | | | SHEET 2 OF 5 | | | | |
| DO NOT SCALE DRAWING | | | CAD: ALTIUM DESIGNER | | | | |
| | | | | SCALE: 2:1 | | | |

4

3

2

1

TOP ASSEMBLY VIEW

QPA2962-4000

FD3

2/11/20

VG12

VD

VD

P1

RFIN

RFOUT

C1

C4

C7

C5

9990

C6

C2

C8

C3

C9

DUT

FD2

Qorvo SAP NO. 293601

BOTTOM ASSEMBLY VIEW

B

A

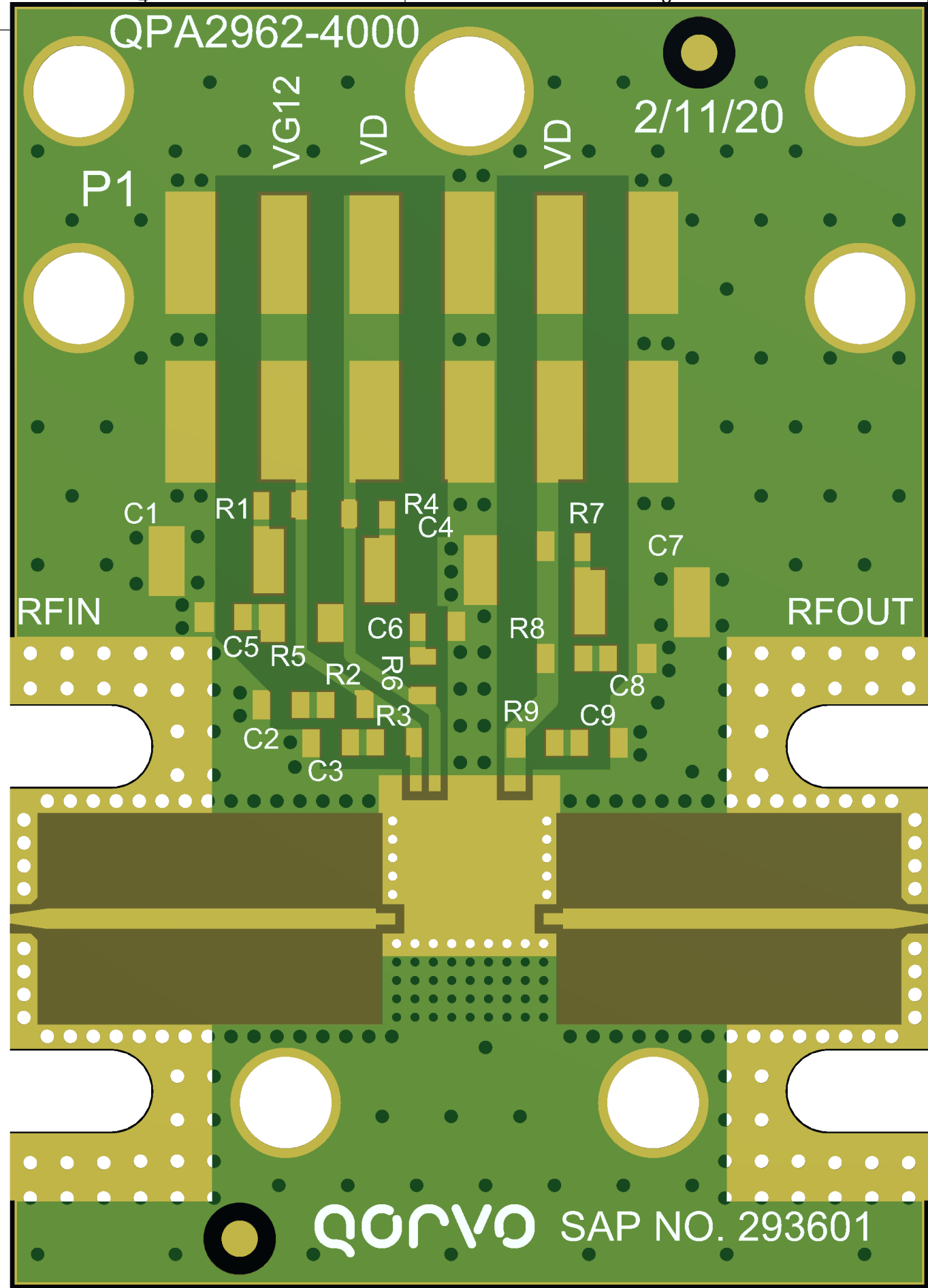
4

3

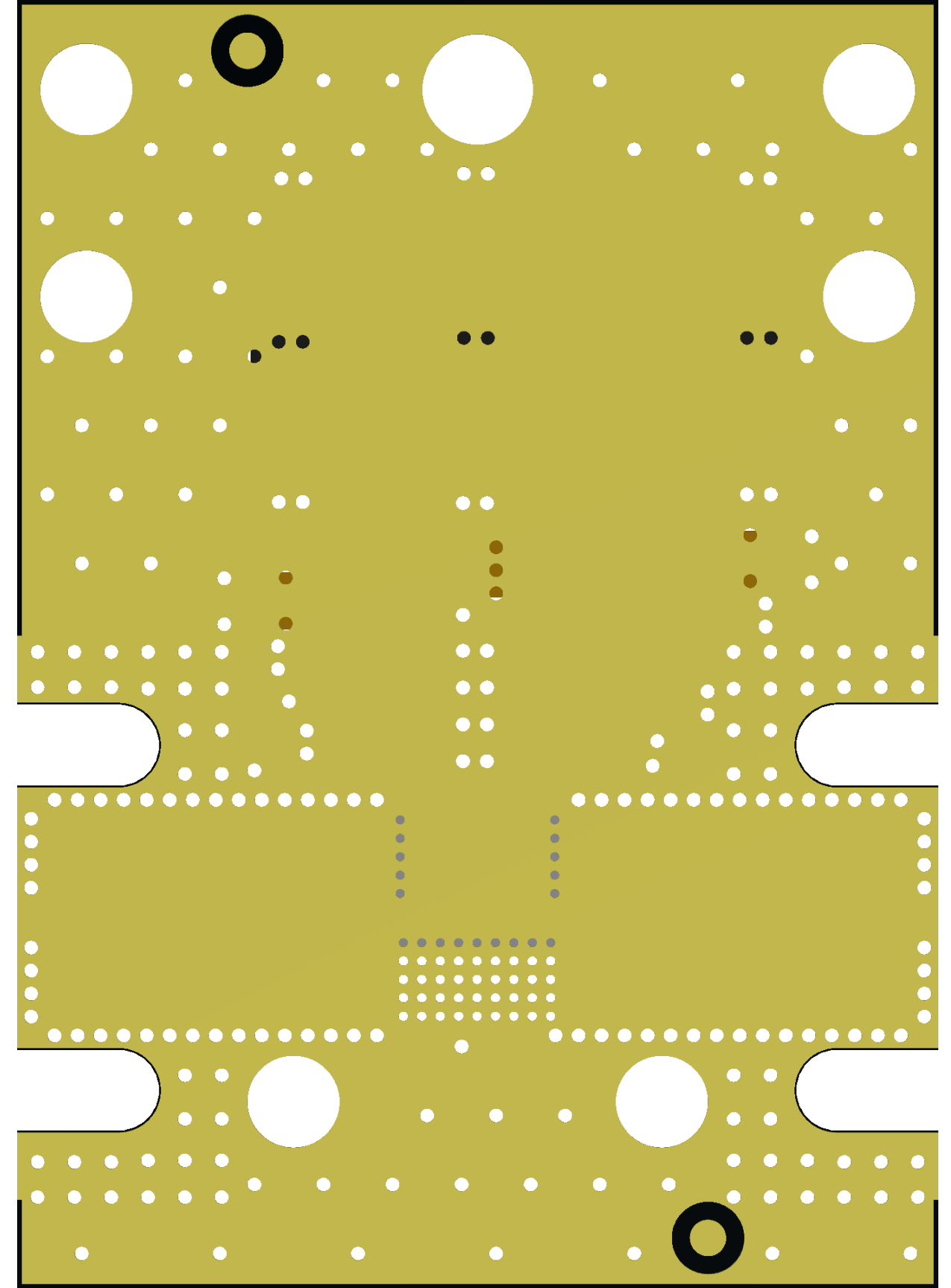
2

1

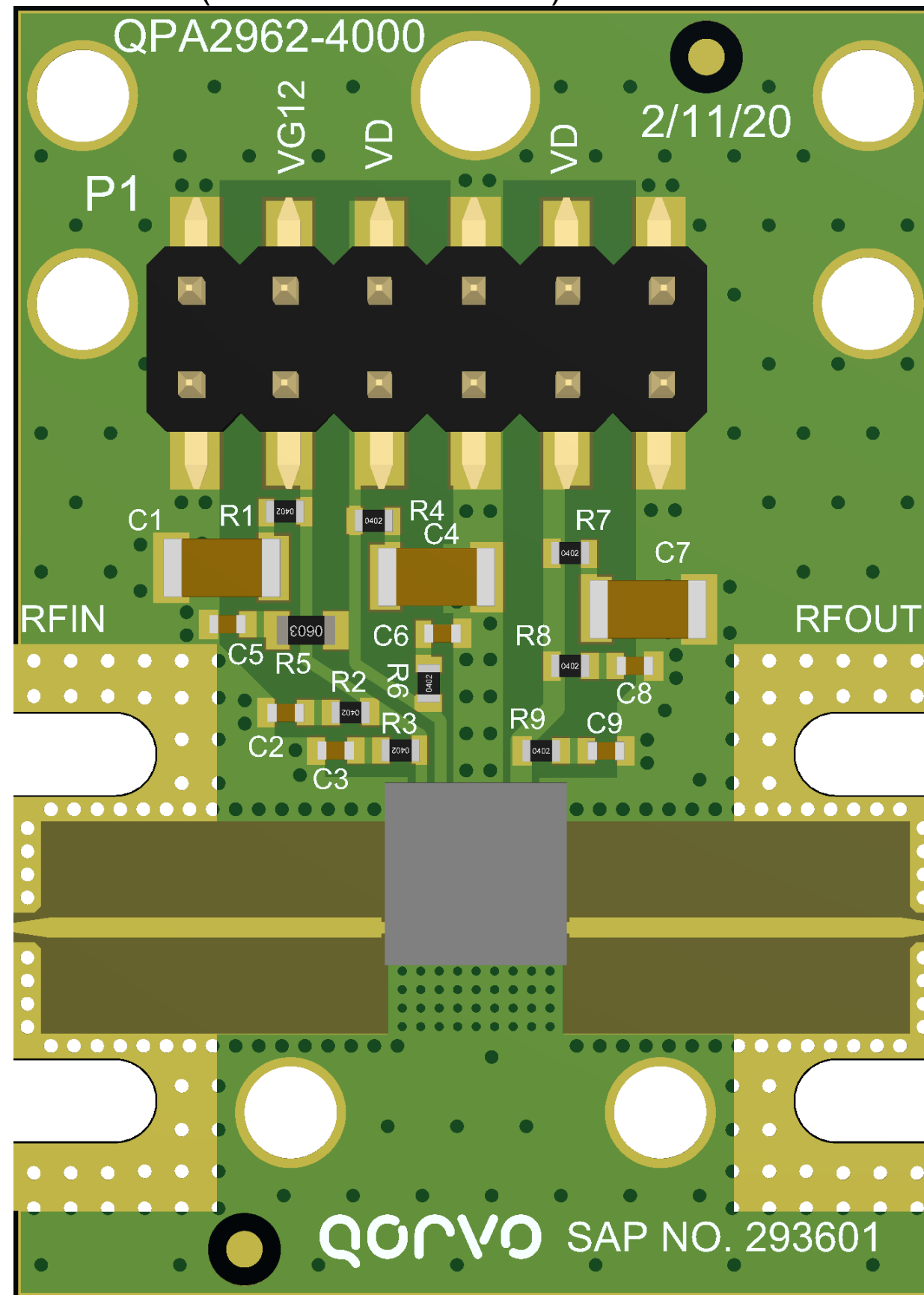
Top view



Bottom View



TOP VIEW (FULLY POPULATED)



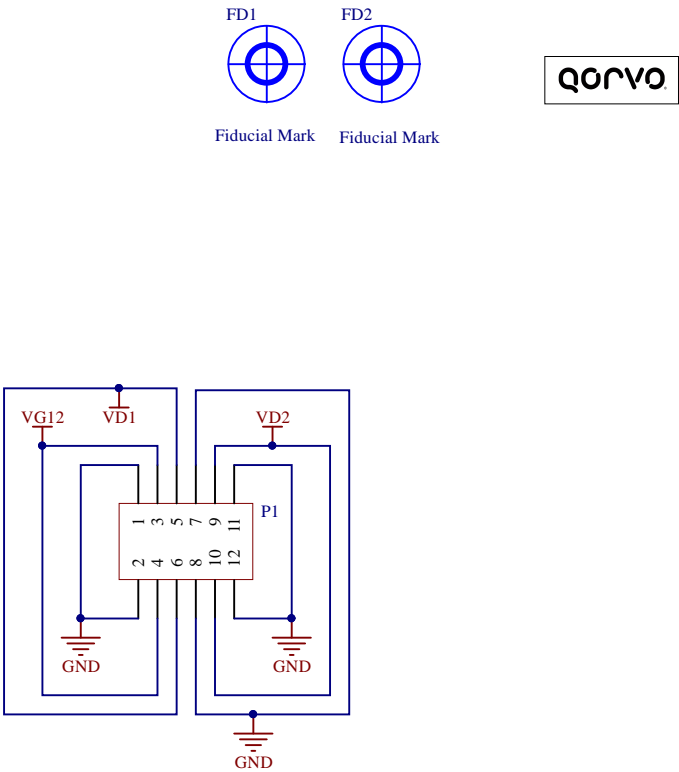
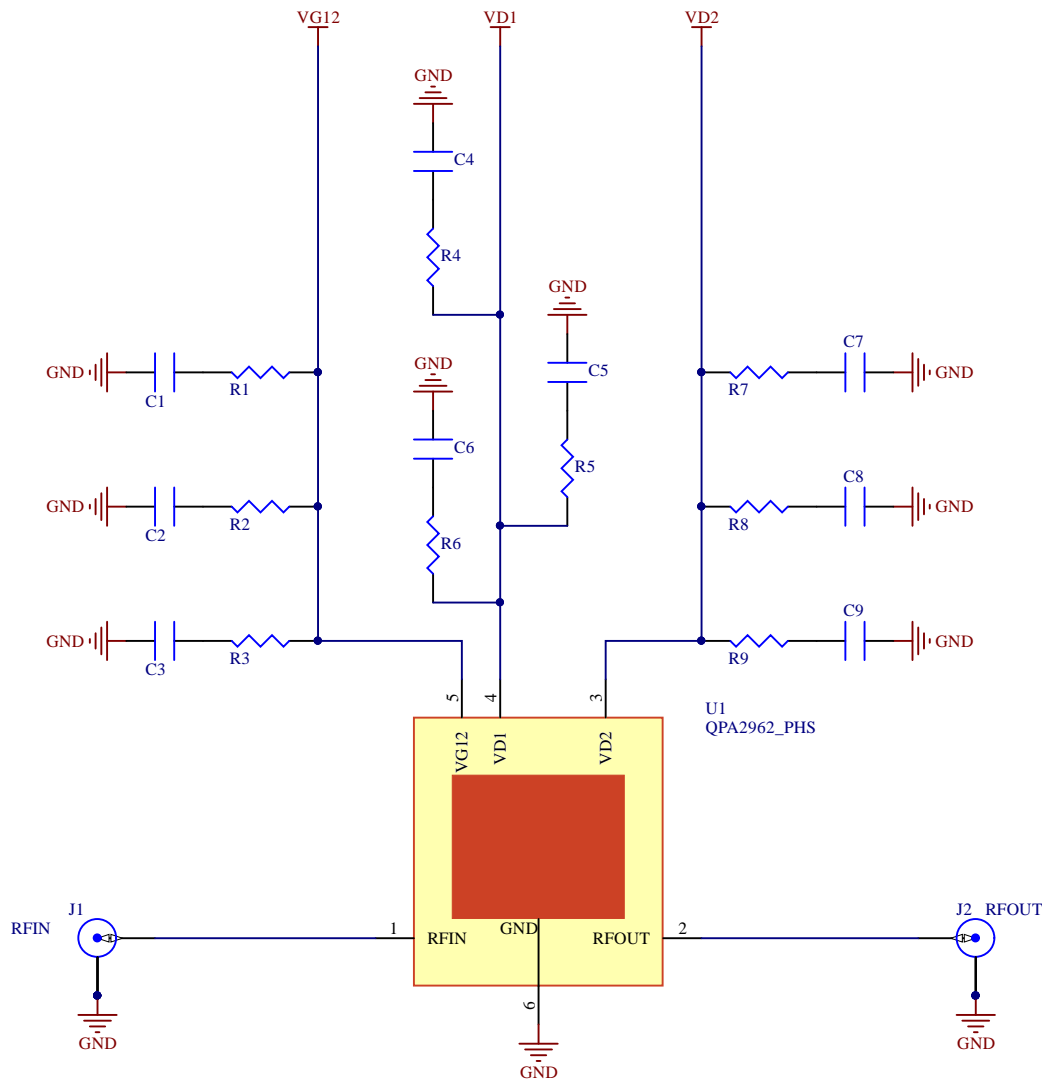
B


B

A

A

| REVISION HISTORY | | | |
|------------------|-----------------|-----------|-----------|
| REV | DESCRIPTION | DATE | APPROVAL |
| A | INITIAL RELEASE | 2/11/2020 | O.MARRUFO |



| | | | |
|---|-----------|---|----------------------------------|
| SAP MATERIAL NUMBER: 293601 | |  | |
| APPROVAL AND RELEASE RECORDS MAINTAINED IN PDE | DATE | | |
| DESIGNER | O.MARRUFO | TITLE: QPA2962 EVALUATION PCB DESIGN PACKAGE | |
| ENGR. | W.SHU | | |
| PDE CONTROLLED | | SIZE B | DOCUMENT NUMBER: QPA2962-4000 |
| | | SCALE: NTS | PROTOTYPE INSTANCE: N/A |
| | | REV. A | |
| | | SHEET 1 OF 1 | |